

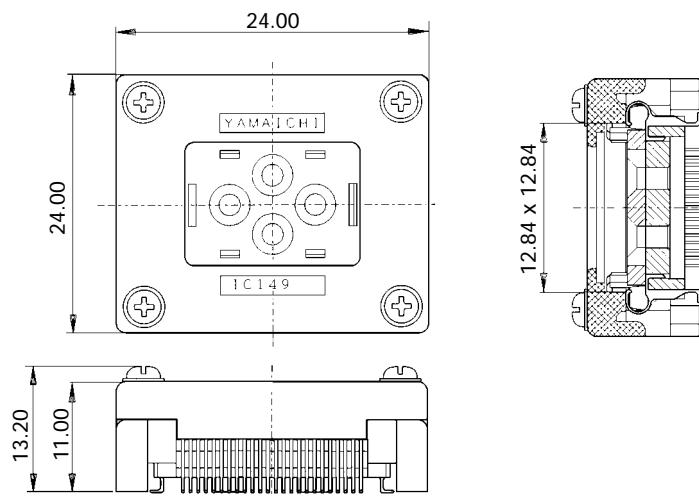
Specifications

Insulation Resistance:	500MΩ at 150V DC
Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute
Contact Resistance:	30mΩ max. at 10mA and 20mV
Operating Temp. Range:	-25°C to +85°C
Reflow-soldering Temp.:	220°C for 60 seconds
Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

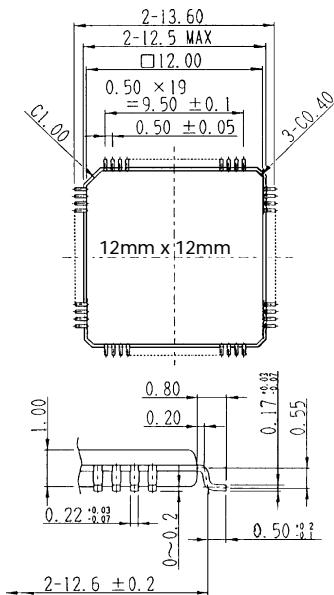
Materials and Finish

Housing:	Polyphenylenesulfide (PPS) glass filled UL94V-0
Contact:	Beryllium Copper (BeCu)
Plating:	SnPb 2.0 ~ 4.0µm over 2.5 ~ 4.5µm Ni = S5 Au 0.3µm min. over 2.5 ~ 4.5µm Ni = B5

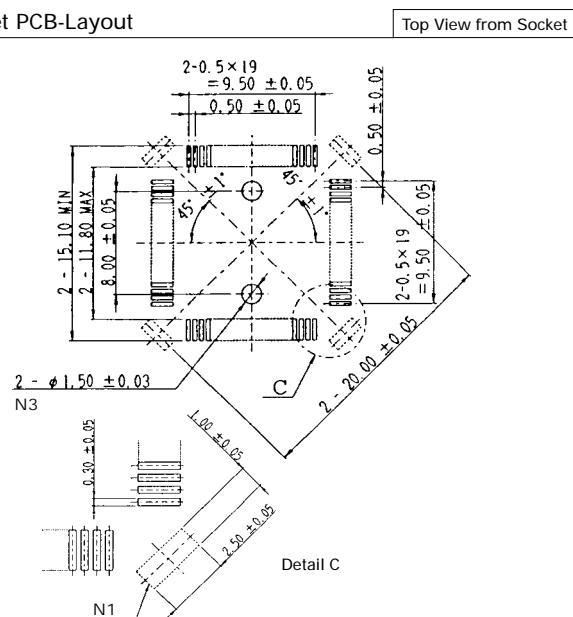
Outline Socket Dimensions (Reference Only)



IC - Dimensions



Socket PCB-Layout



Notes

N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.

N3: These holes are only necessary for use with positioning pins.

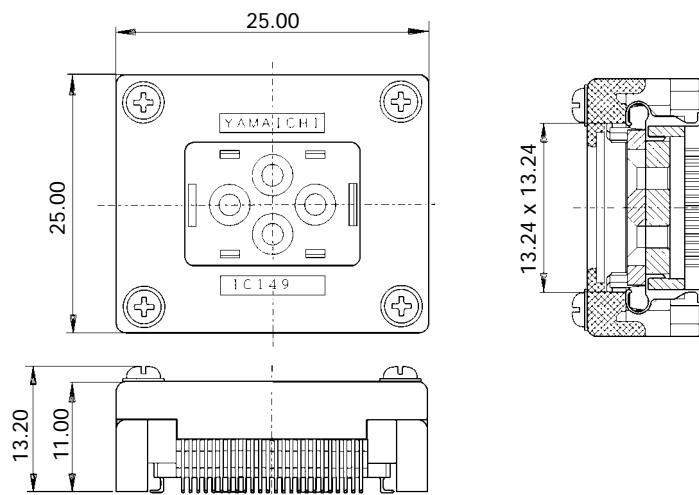
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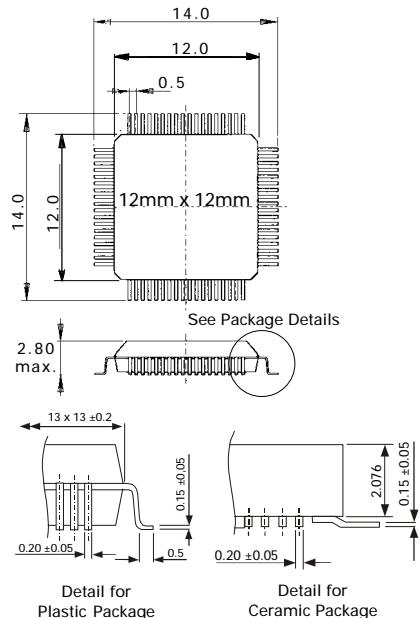
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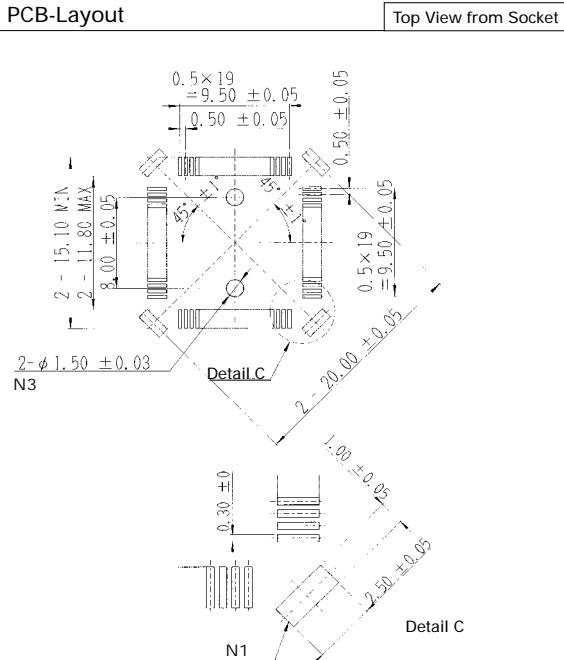
Outline Socket Dimensions (Reference Only)



IC - Dimensions



Socket PCB-Layout



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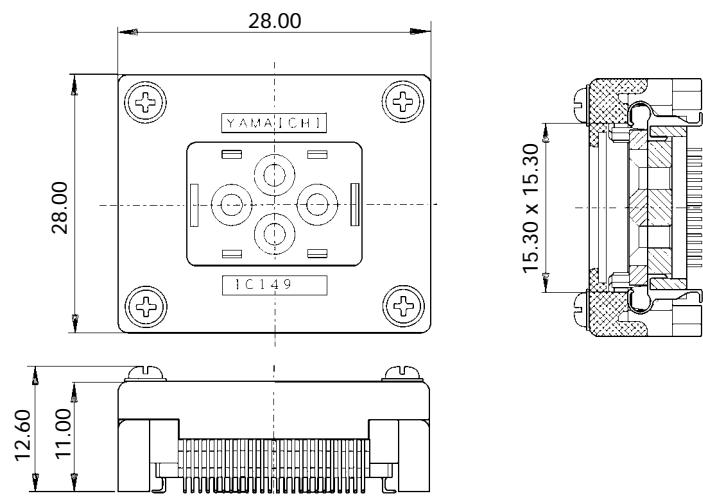
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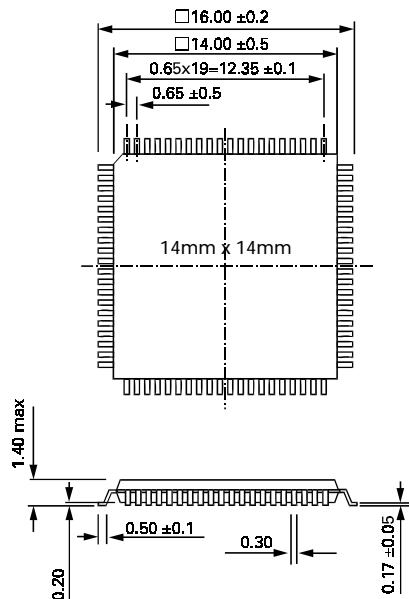
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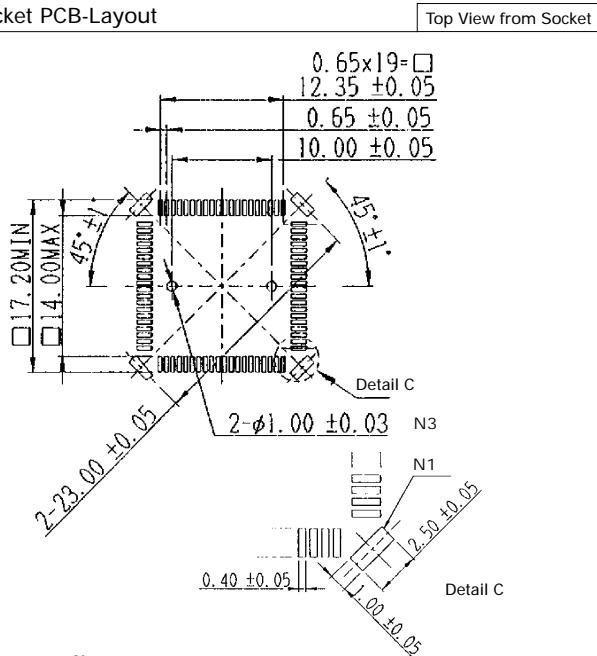
Outline Socket Dimensions (Reference Only)



IC - Dimensions



Socket PCB-Layout



Notes

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Part Number (Details)

IC149 - 080 - *51 - *5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

Contact Plating:

S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

Compatible Emulation-Adapter ICP-080-7

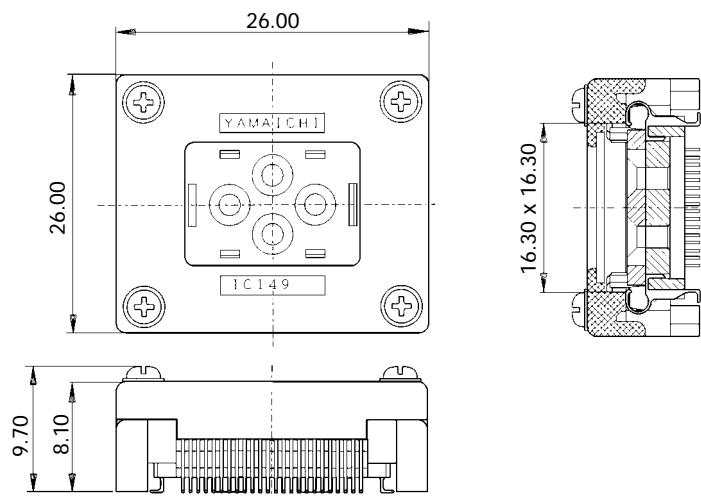
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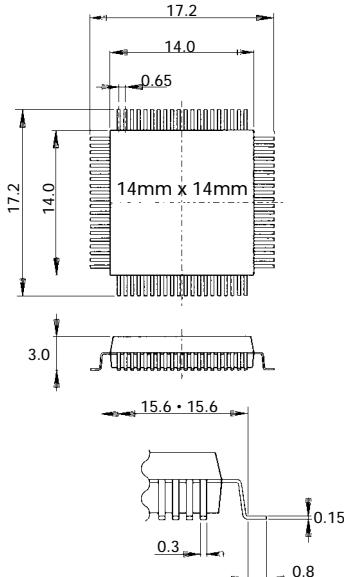
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Outline Socket Dimensions (Reference Only)

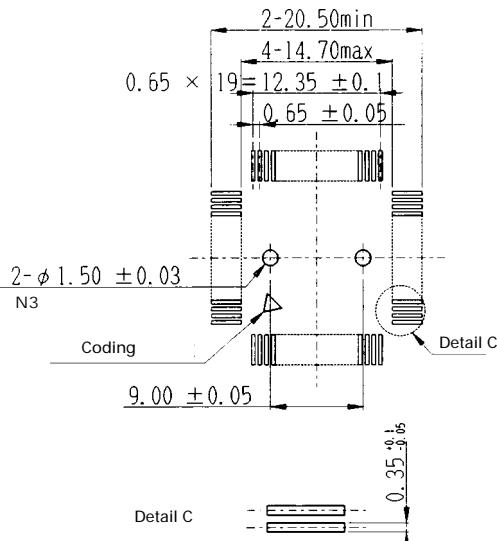


IC - Dimensions



Socket PCB-Layout

Top View from Socket



Notes

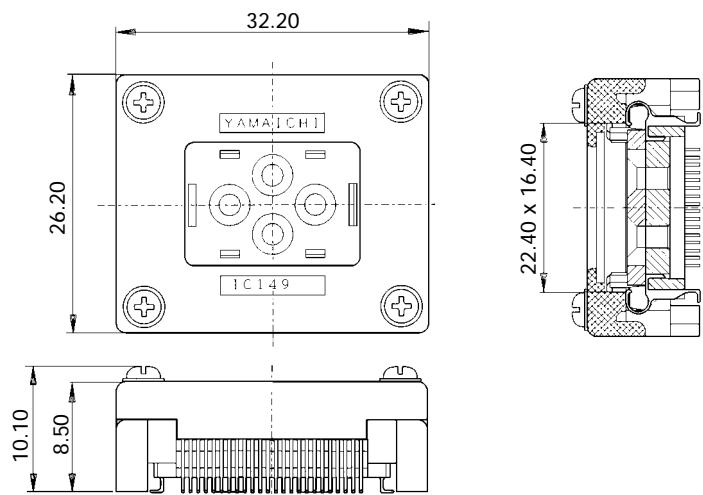
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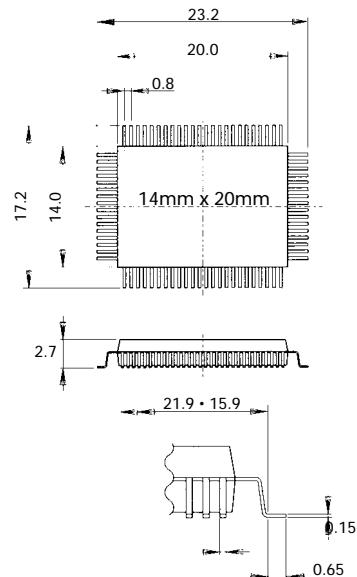
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Contact: Beryllium Copper (BeCu)
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Outline Socket Dimensions (Reference Only)



IC - Dimensions



Part Number (Details)

IC149 - 080 - *21 - *5

Series No.

No. of Contact Pins

Positioning: Dino

0 = Without P

Contact Plating:

S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

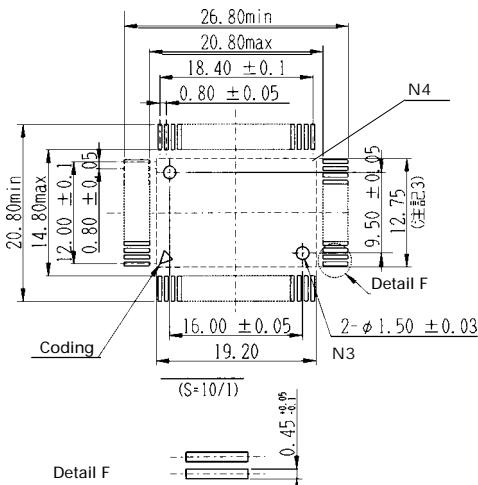
Compatible Emulation-Adapter ICP-080-5

Remarks

1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

Socket PCB-Layout

Top View from Socket



Notes

N3: These holes are only necessary for use with positioning pins.
N4: The Socket may be glued to the PC Board within this area.

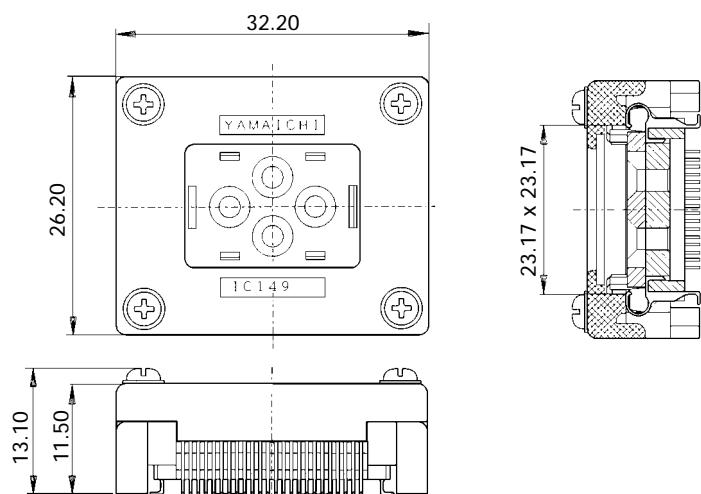
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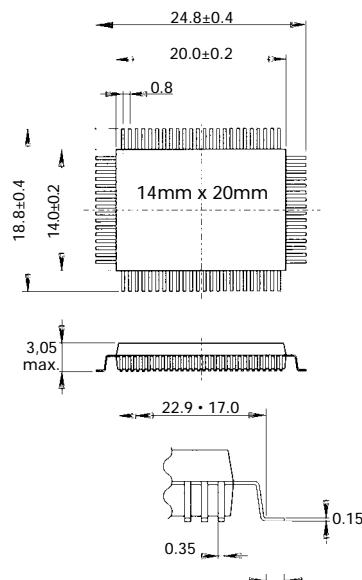
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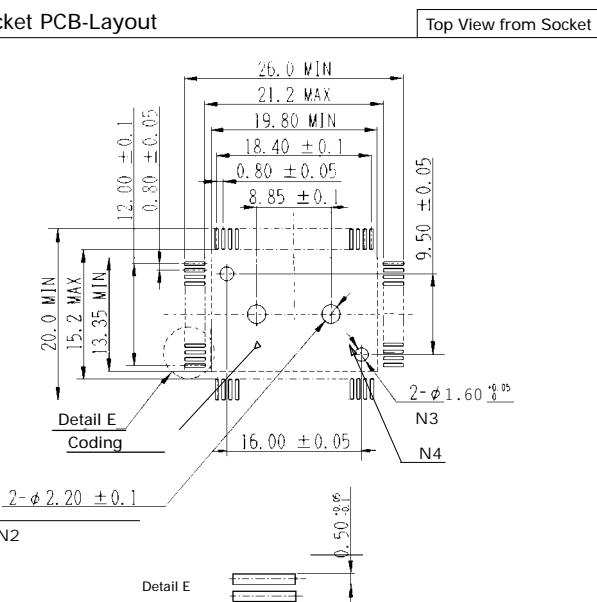
Outline Socket Dimensions (Reference Only)



IC - Dimensions



Socket PCB-Layout



Notes

- N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.
- N2: These holes are only necessary when fixing the Socket with screws.
- N3: These holes are only necessary for use with positioning pins.
- N4: The Socket may be glued to the PC Board within this area.